

Multilayer Power Inductor

CIG10W Series (1608/ EIA 0603)



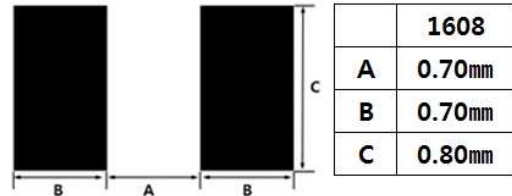
APPLICATION

Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

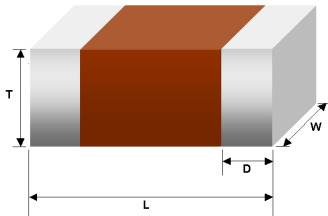
FEATURES

- The smallest multilayer power inductor(1.6mmx0.8mm)
- Lower Profile (0.8mm max)
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances

RECOMMENDED LAND PATTERN



DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
10	1.6±0.15	0.8±0.15	0.8±0.15	0.3±0.2

DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG10WR27MNC	0603/1608	0.27±25%	0.12 ±25 %	1.30
CIG10WR47MNC	0603/1608	0.47±20%	0.15 ±20 %	1.10
CIG10W1R0MNC	0603/1608	1.0±20%	0.20 ±20 %	0.95
CIG10W1R5MNC	0603/1608	1.5±20%	0.25 ±20 %	0.80
CIG10W2R2MNC	0603/1608	2.2±20%	0.30 ±20 %	0.75
CIG10W3R3MNC	0603/1608	3.3±20%	0.40 ±20 %	0.70
CIG10W4R7MNC	0603/1608	4.7±20%	0.50 ±20 %	0.62

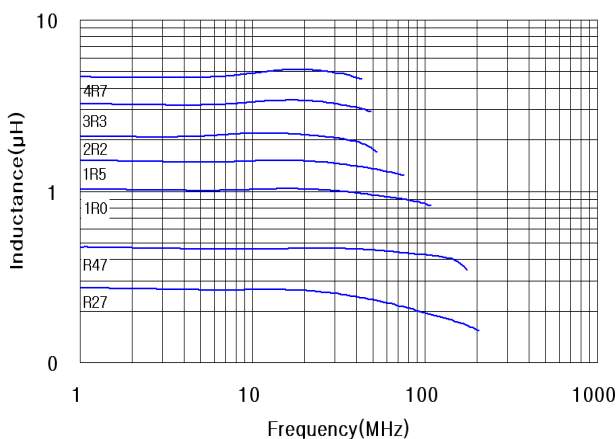
※Rated Current: DC current value when the self-generation of heat rises to 40°C (Reference ambient temperature:25°C)

※Operating temperature range: -40 to +125°C (Including self-temperature rise)

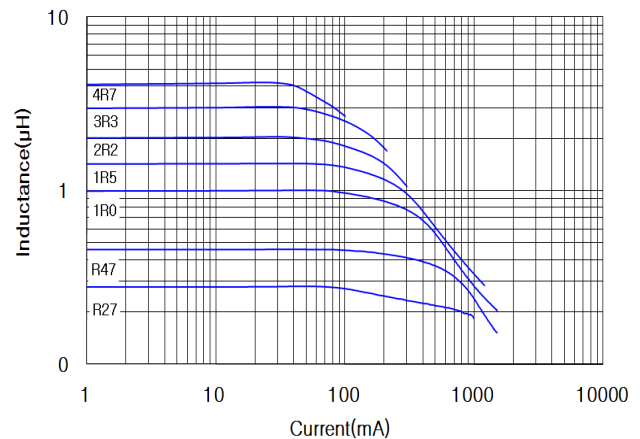
※Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics(Typ.)



2) DC Bias characteristics (Typ.)



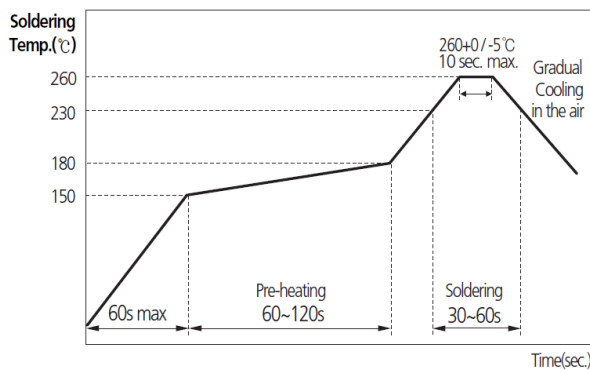
PRODUCT IDENTIFICATION

CI G 10 W 2R2 M N C
(1) (2) (3) (4) (5) (6) (7) (8)

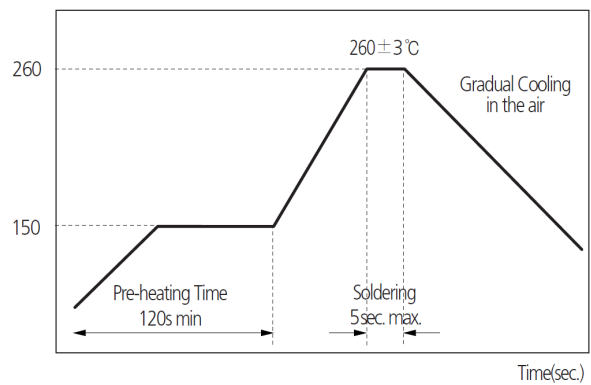
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (W:Normal Type)
- (5) Inductance (R47:0.47uH, 2R2:2.2uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4,000

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.